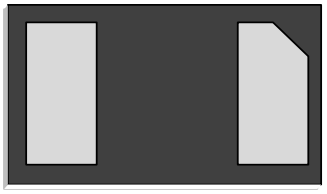
Features

- 495 Watts Peak Pulse Power per Line (t_p = 8/20μs)
- Protects one I/O or power line
- Low Clamping Voltage
- Working Voltage: 24 V
- Low Leakage Current
- AEC-Q101 Qualified



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IEC Compatibility (EN61000-4)

- IEC 61000-4-2 (ESD) ±30kV (air), ±30kV (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 9A (8/20μs)

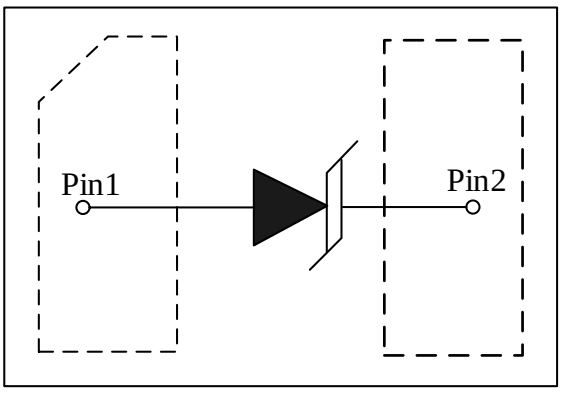
Mechanical Characteristics

- DFN1006-2L package
- Marking: Marking Code
- Packaging: Tape and Reel
- RoHS Compliant

Applications

- Cellular Handsets & Accessories
- Personal Digital Assistants (PDAs)
- Notebooks & Handhelds
- Portable Instrumentation
- Digital Cameras
- MP3 players

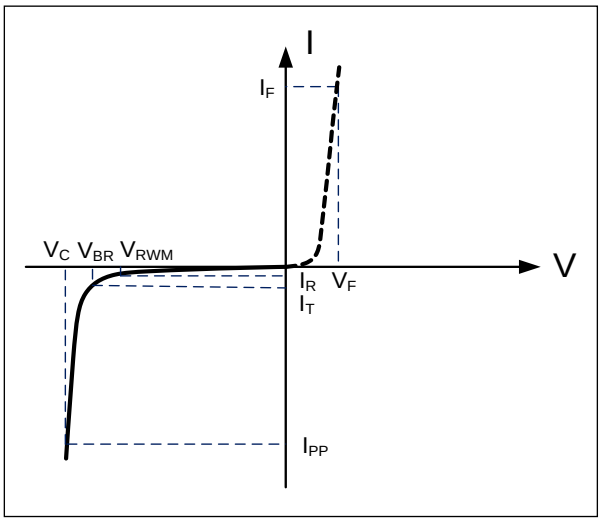
Schematic & PIN Configuration



Absolute Maximum Rating			
Rating	**Symbol**	**Value**	**Units**
Peak Pulse Power（t_p =8/20μs）	P_{PP}	495	Watts
Peak Pulse Current (t_p =8/20μs)	I_{pp}	9	A
Operating Temperature	T_J	-55 to + 125	℃
Storage Temperature	T_{STG}	-55 to +150	℃

Electrical Parameters (T=25℃)

Symbol	Parameter
I_{PP}	Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Reverse Stand-Off Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F



Electrical Characteristics

DW24DF-AT-S						
Parameter	**Symbol**	**Conditions**	**Minimum**	**Typical**	**Maximum**	**Units**
Reverse Stand-Off Voltage	V_{RWM}				24	V
Reverse Breakdown Voltage	V_{BR}	I_T=1mA	26.7			V
Reverse Leakage Current	I_R	V_{RWM}=24V,T=25℃			500	nA
Forward Voltage	V_F	I_F=10mA	0.5		1	V
Clamping Voltage	V_C	I_{PP} = 9A,tp = 8/20μs		51	55	V
Dynamic Resistance[1,2]	R_{DYN}	TLP=0.2/100ns		0.4		Ω
ESD Clamping Voltage[1]	V_C	IPP = 4A, tp = 0.2/100ns (TLP)		33		V
ESD Clamping Voltage[1]	V_C	IPP = 16A, tp = 0.2/100ns (TLP)		38		V
Junction Capacitance	C_j	V_R = 0V, f = 1MHz		45	55	pF

Notes：1、TLP Setting：t_p=100ns, t_r=0.2ns, I_{TLP} and V_{TLP} sample window:t_1=70ns to t_2=90ns.
2、Dynamic resistance calculated from I_{PP}=4A to I_{PP}=16A using “Best Fit”.

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Typical Characteristics

Figure 1: Peak Pulse Power vs. Pulse Time

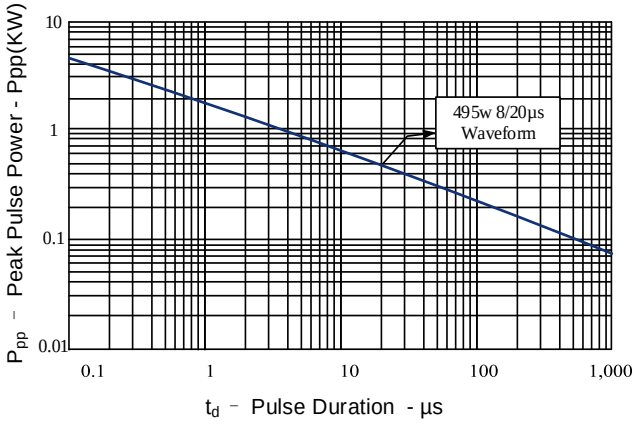


Figure 2: Power Derating Curve

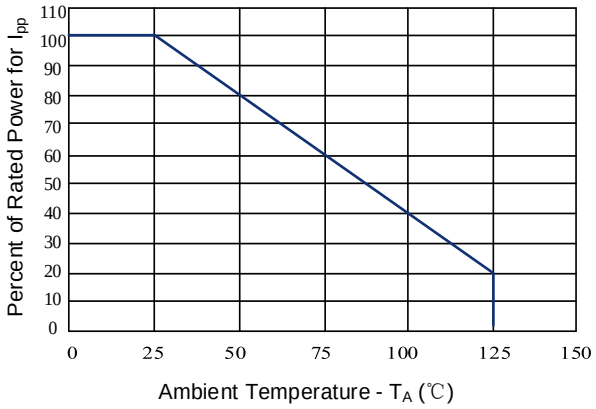


Figure 3: Clamping Voltage vs. Peak Pulse Current

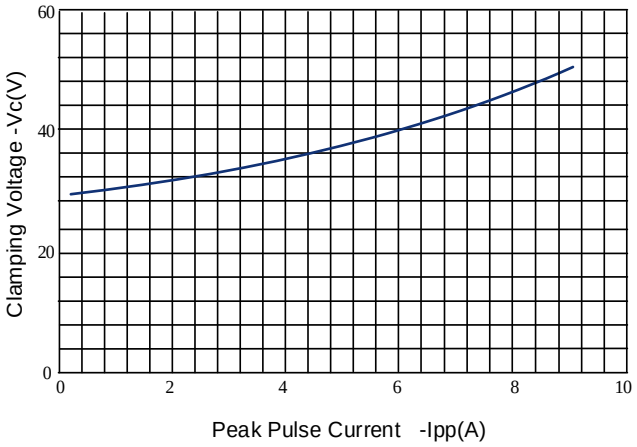


Figure 4: Normalized Junction Capacitance vs. Reverse Voltage

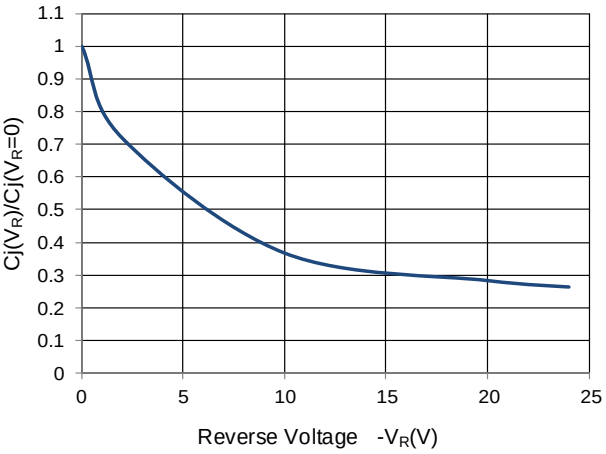


Figure 5: 8/20μs Pulse Waveform

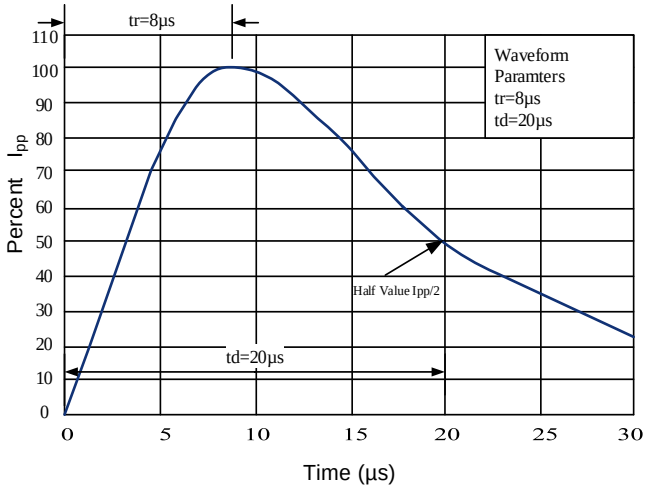
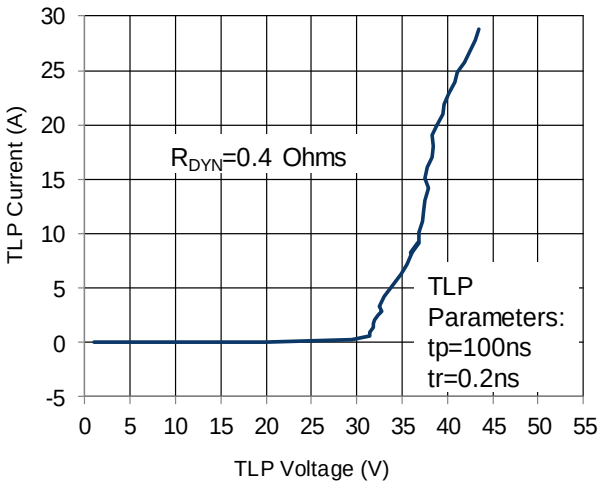
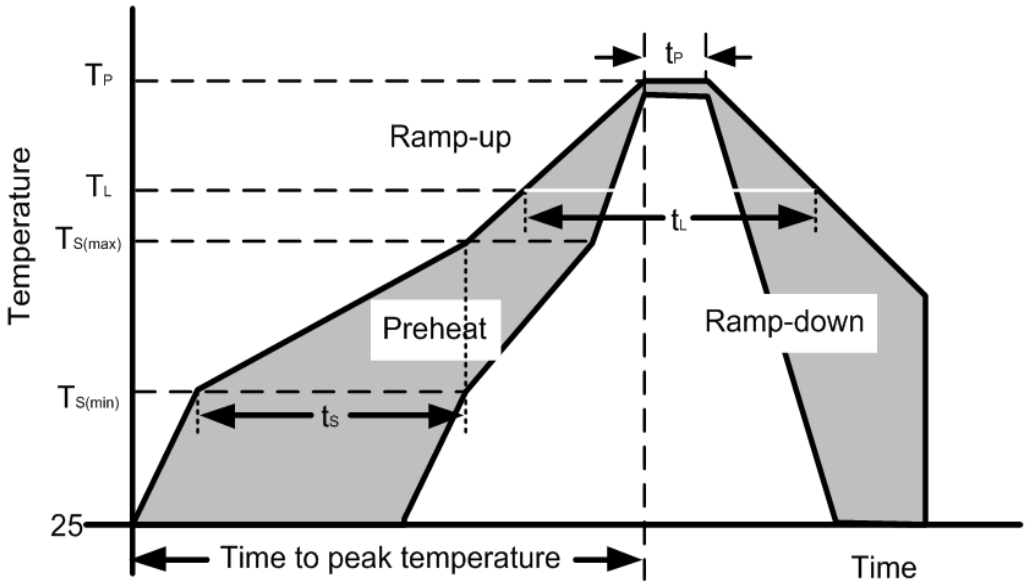


Figure 6: TLP I-V Curve



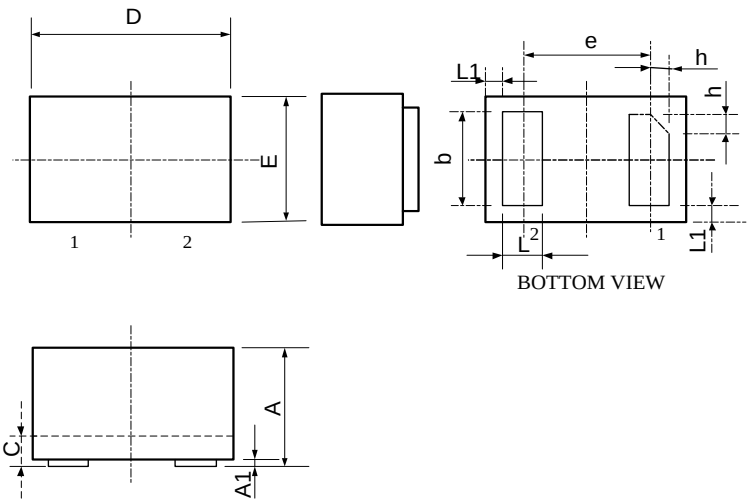
Soldering Parameters

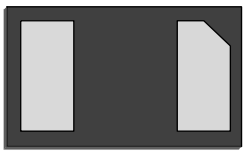
Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (ts)	60 – 190 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{S(max)}$ to T_L——Ramp-up Rate		5°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		260+0/-5 °C
Time within actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		280°C



Outline Drawing –DFN1006-2L

PACKAGE OUTLINE





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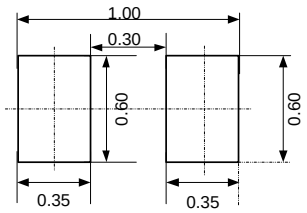
SYMBOL	MILLIMETERS		
	MIN	NOM	MAX
A	0.45	0.50	0.55
A1	0	0.02	0.05
b	0.45	0.50	0.55
C	0.12	0.15	0.18
D	0.95	1.00	1.05
e	0.65BSC		
E	0.55	0.60	0.65
L	0.20	0.25	0.30
L1	0.05REF		
h	0.07	0.12	0.17

Land Pattern



Marking Codes

Part Number	Marking Code
DW24DF-AT-S	

Package Information

Qty：10k/Reel